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(71)Applicant: SHINKO ELECTRIC IND CO LTD

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(72)Inventor: WAKABAYASHI NORIO

MURATA AKIHIKO

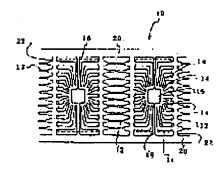
## (54) LEAD FRAME FOR SEMICONDUCTOR DEVICE

(57) Abstract:

PURPOSE: To obtain a lead frame for a semiconductor device to improve solderability by Ag-plating a thin Pd or Pd alloy

film or forming an Au-plated film.

CONSTITUTION: A Pd or Pd alloy film 24 is formed through a base plated film 26 such as Ni-plated film on the entire material of a lead frame 10, or formed directly on the material according to the quality of the material. An Ag plated or Auplated film 28 is formed on the entire frame 10. or at least formed on outer leads 12, and the film 28 is formed in a thin film of the degree of a single atomic layer. Thus, solder wettability is improved, a wetting time can be shortened, excellent solderability can be provided, and soldering operability can be improved.





## **LEGAL STATUS**

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